

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Original) A method of making a semiconductor device comprising:  
providing a wafer on which are formed electrodes;  
providing a stress relieving layer on the wafer in such as way as to avoid at least a part of the electrodes, the stress relieving layer formed to have a sloping edge;  
forming wiring over the stress relieving layer from the electrodes, a width of the wiring being greater than a width of each of the electrodes at a junction of the wiring and each of the electrodes, the wiring formed to have a narrower portion on the sloping edge than one of the electrodes;  
forming external electrodes connected to the wiring above the stress relieving layer; and  
cutting the wafer into individual pieces.
2. (Canceled)